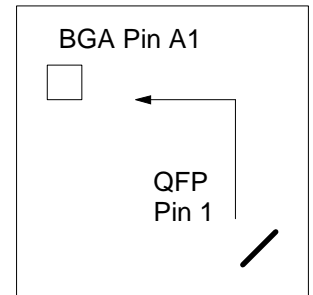
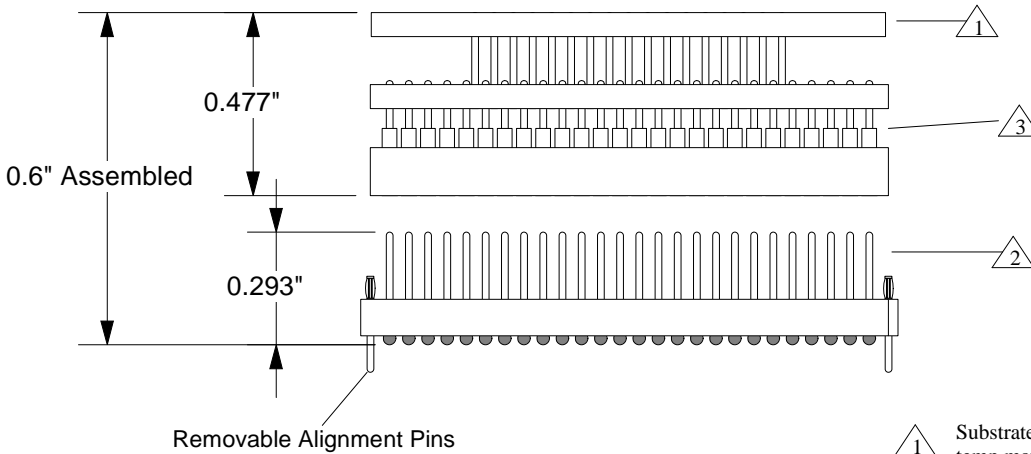


Relative Orientations




Side View



- ① Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- ② Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- ③ Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)

Description: PACKAGE CONVERTER
 208 position PQFP to 352 position BGA. Altera Max 9320 to Xilinx XC95XX.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

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		Drawing by: W. Watson		Date: 11/3/98
		File: DC-QFP/BGA-95XX-S-B-01 Dwg	Modified:	